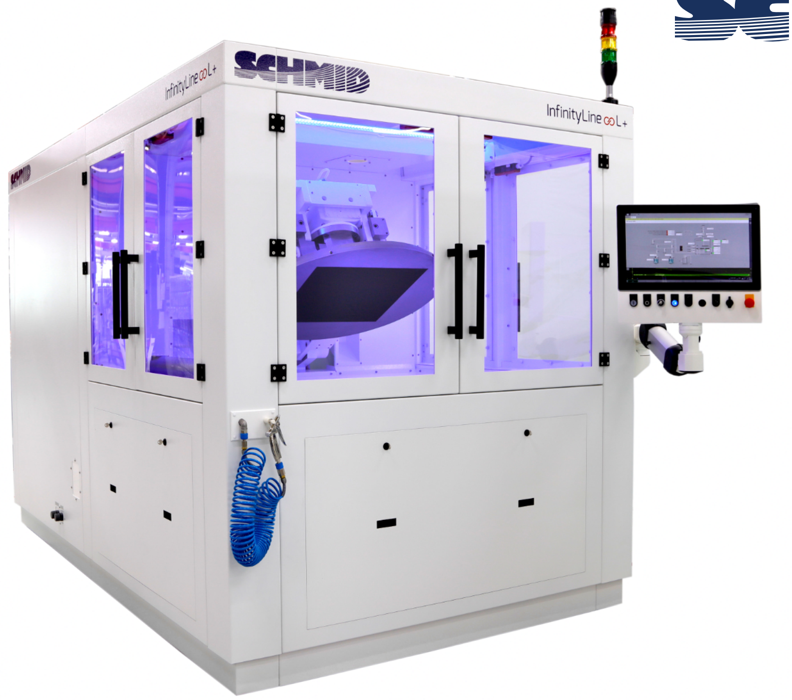


InfinityLine L+

CMP Cluster - Precision Polishing for Next-Generation Substrates.

Our InfinityLine L+ enables highly uniform and controlled planarization across a wide range of substrate and glass materials. Seamlessly integrated process steps ensure optimal performance, resource efficiency, and maximum system uptime.
The modular cluster concept allows flexible configuration and combination of multiple processes within a single platform.

- Chemistry Mixing
- Clamping
- Soft Touch Polishing
- Polishing
- Delution

Key Performance Indicators

Panel Size	Max 635mm x 635mm / 24.5'' x 24.5''	**Panel Thickness Substrate**	Minimum: 35µm glass Maximum: 3mm
Panel Thickness for Glass	623mm x 623mm / 24.5'' x 24.5''	**Capabilitiy**	ABF: 0.5 - 1.0µm/min. Cu: 2.0 - 3.0µm/min.

Other dimensions on demand

Contact:
electronics@schmid-group.com
www.schmid-group.com

Process Highlights

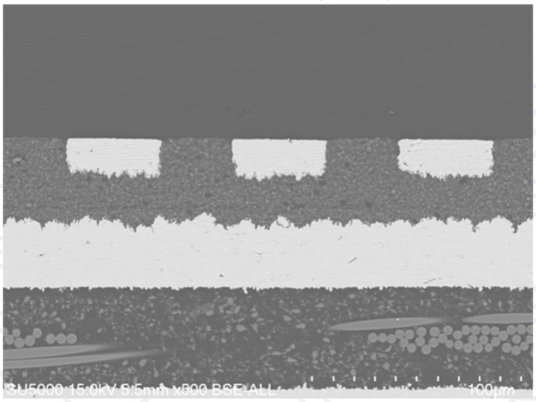
Achieve superior planarity and maximum process stability across glass and organic substrates.

Patented process control ensure outstanding results and high production efficiency.

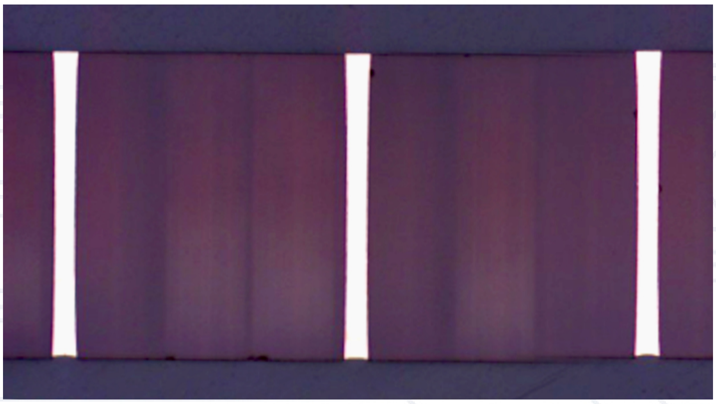
- Maximum stability for fragile materials through advanced clamping and pressure control
- Superior uniformity enabled by the ''Oscar'' slurry system and active cooling
- Broad material compatibility - glass, organic build-up layers, and advanced packaging substrates
- Scalable automation with cluster integration, FOUP handling, and double-sided processing
- Maximum uptime and low cost of ownership through modular design and quick-change consubables
- Seamless inline cleaning (InfinityLine H+) for residue-free, dry substrate

Process Results

DMP of ABF Build Up Layer



TGVs after CMP



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